

REMARKS

A marked copy of the original specification is also provided for the Examiner's review. It is noted that the substitute specification merely corrects minor informalities and improves grammar and idiomatic expression. The undersigned attorney hereby states that no new matter is added by the substitute specification. Accordingly, it is respectfully submitted that the substitute specification be entered to replace the original specification. Entry of the preliminary amendments and examination of the application is respectfully requested.

Attached hereto is a marked-up version of the changes made to the abstract by the current amendment. The attached page is captioned "Version with markings to show changes made."

If the Examiner believes that there are any other points which may be clarified or otherwise disposed of, either by telephone discussion or by personal interview, the Examiner is invited to contact applicants' undersigned attorney at the number indicated below.


To the extent necessary, the applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit

account of Antonelli, Terry, Stout & Kraus, Deposit Account
No. 01-2135 (500.39590X00).

Respectfully submitted,

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By



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

RECEIVED
JUN 18 2002
TC 2800 MAIL ROOM

(09785452)

ABSTRACT OF THE DISCLOSURE

Arrangements are provided to [The invention provides means for] effectively prevent [preventing a] wire disconnection generated due to an increase of heat [calorie] applied to a semiconductor integrated circuit device. The semiconductor integrated circuit device is structured such that a metal layer containing a Pd layer is provided in a portion to which a connecting member having a conductivity is connected, and an alloy layer having a melting point higher than that of an Sn-Pb eutectic solder and containing no Pb as a main composing metal is provided outside a portion molded by a resin. Further, a metal layer in which a thickness in a portion to which the connecting member having the conductivity is adhered is equal to or more than 10 μm is provided in the connecting member.